



**BOARD LEVEL COOLING - 3749**

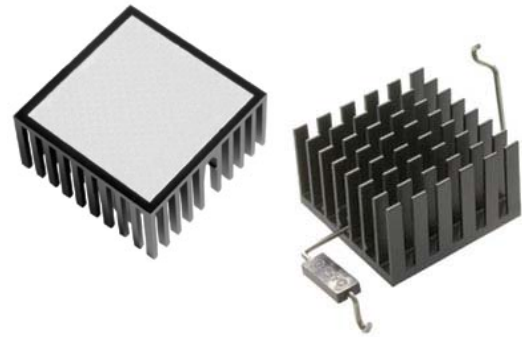
3749 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative image only.

**ORDERING INFORMATION**

Part Number	Device Type
374924B00035G	BGA, FPGA
374924B60024G	BGA, FPGA

**HEAT SINK DETAILS**

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options: 374924B00035G	Tape
Device Attachment Options: 374924B60024G	Solder Anchor Clip
Thermal Interface Material: 374924B00035G	T411 Chomerics Tape for All Surfaces
Thermal Interface Material: 374924B60024G	T766 Chomerics Phase Change for All Surfaces

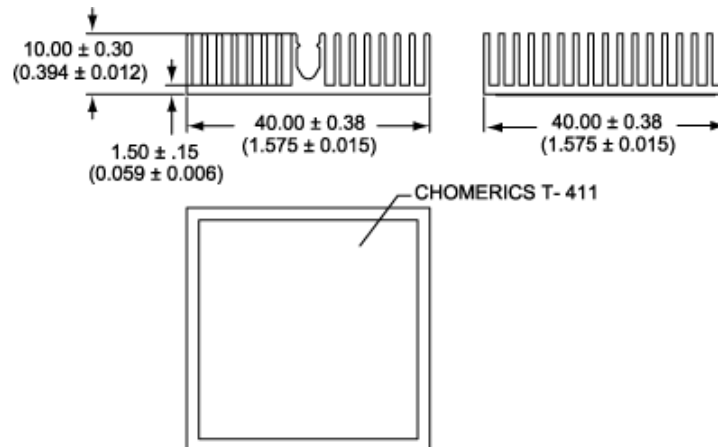


Property	Details
Heat Sink Width (mm)	40.00
Heat Sink Length (mm)	40.00
Heat Sink Height (mm)	10.00
Heat Sink Mounting Direction	Horizontal, Vertical

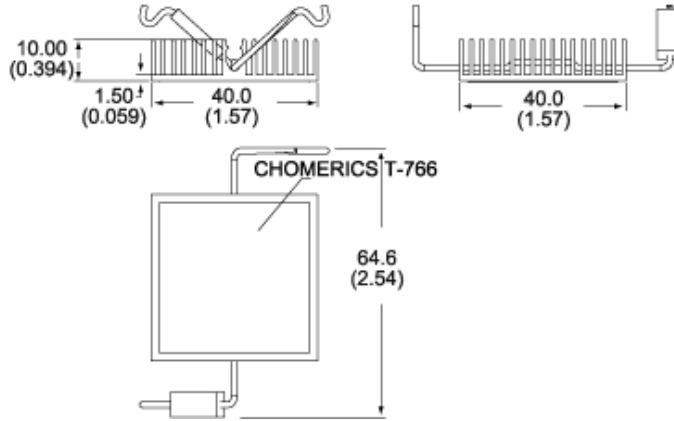
**MECHANICAL & PERFORMANCE**

Drawing dimensions are shown in mm, (in)

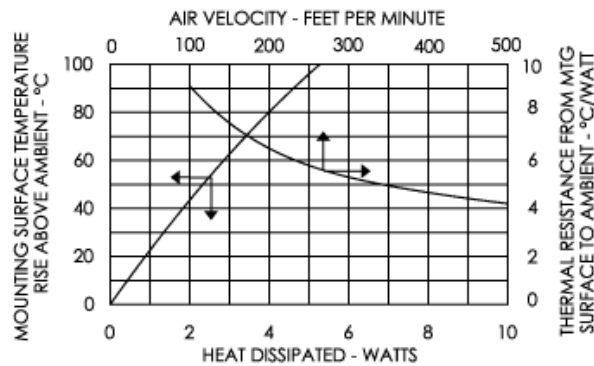
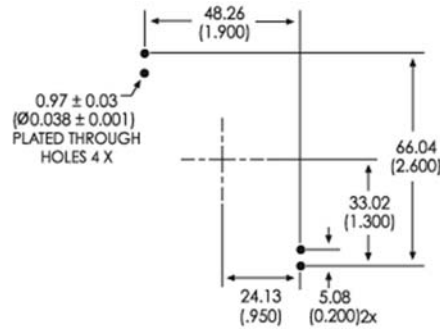
Part Number: 374924B00035G



Part Number: 374924B60024G



*Mounting Details:*



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